

LLRF4.6 Evaluation Board

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July 7, 2014

Introduction

This document is an update of LLRF4 documentation packet, describing up-to-date information on 2013 LLRF4.6 revision of the board. The main difference between LLRF4 (last revision 4.2, dated 2009-06-28) and LLRF4.6 is the FPGA. The updated board uses Spartan-6 FPGA in CS324 package. Normally, the boards are assembled with the largest and fastest part fitting the footprint — XC6SLX45-3CSG324. While smaller parts can be used, there is little rationale to do so.

Besides the component changes, several new or improved features have been incorporated:

- Transition from Spartan-3 XC3S1000 to Spartan-6 XC6SLX45;
- New FPGA core supply switcher capable of 2.5 A;
- Power supply jumpers replaced by zero ohm resistors;
- Maximally flat PCB backside for thermal pad mounting on cold plate;
- Reduced parasitics on RF/IF inputs
- High quality stripline LO distribution network, capable of 3 GHz;
- LO 1:8 splitter works to 3.4 GHz;
- LVDS signals routed as 100 Ω differential lines;
- LVDS termination resistors deleted;
- DS1822 thermometer in TO-92 replaced by DS18B20 in SO-8;
- Improved input channel shielding assembly.

The rest of this paper walks through these changes in detail.

FPGA

LLRF4.6 transitions to a more modern Xilinx FPGA. The part is also slightly faster than the old Spartan-3. A short summary of differences between the two parts is shown below. Of course, logic cells comparison is imprecise, since Spartan-6 uses new 6-input LUT architecture. Xilinx uses some fudge factors to convert slice counts to vague “logic cells”.

	XC3S1000	XC6SLX45	Notes
Logic cells	17280	43661	
Multipliers	24	58	DSP48A1 in S6
BlockRAM	24	116	18kbits

One quirk of LLRF4.6 FPGA setup is that two data bits on high-speed DAC interface are driven by dual function pins R15 (IO_L1P_CCLK_2) and V10 (IO_L30N_GCLK0_USERCCLK_2). The bitfile must be generated with startup clock set to CCLK (-g StartUpClk:CCLK option of bitgen) for these pins to function as user outputs.

RF/LO Subsystem

At the RF input, parallel LC matching network was removed (never used on the original LLRF4, layout considerations).

LO 1:8 power splitter (4 input mixers, 2 output mixers, power monitor, monitor connector) is now built from 7 Mini-Circuits QCN-series quadrature splitters. These parts cover the range from 220 MHz to 3.4 GHz in multiple bands.

The following parts can be used to populate the board according to the desired LO and RF frequencies:

U13, U21, U22, U23, U24, U25, U26: 2-way LO splitter

220-470 MHz	QCN-3+
330-580 MHz	QCN-5+
425-675 MHz	QCN-7+
450-750 MHz	QCN-8+
800-1375 MHz	QCN-12+
675-1300 MHz	QCN-13D+
1100-1925 MHz	QCN-19+
1350-2450 MHz	QCN-25+
1700-2700 MHz	QCN-27+
2500-3400 MHz	QCN-34+

M1, M2, M101, M102, M103, M104: level 13 mixer

40-2500 MHz	SYM-25DMHW
5-3000 MHz	SYM-30DMHW

RF down- and up-conversion can also be bypassed during production.

IF filters

Many different IF filter designs have been developed for the original LLRF4. Most of these should work well with LLRF4.6. Some have already been updated and tested on the revised board — see the table below. CF is center frequency, BW is the bandwidth, level refers to the bandwidth measurement level (drop in dB from the peak). For narrow filters, 3 dB measurement is appropriate, for wider ones, 1 and 0.5 dB bandwidth is specified. In all cases, full bandwidth from lower to upper magnitude drop points is listed.

	CF (MHz)	BW (MHz)	Level (dB)	FS (dBm)
Tested on LLRF4.6				
50 MHz (original)	48.5	9	3	11
39 MHz (Dimtel)	39	5.5	3	-4
74 MHz (Dimtel)	74	11	3	-3
81 MHz (Dimtel)	81	12.4	3	-3
Wideband (J-PARC)	34.1	68.1	0.5	6
Tested on LLRF4.2				
110 MHz (FERMI)	110	58	3	-7
186 MHz (APEX)	190	28	0.5	-5

DAC outputs are also filtered on the board, with a simple two element filter. Original configuration is 150 nH series inductor followed by 100 pF parallel capacitor. This setup has low-pass response with roughly 41 MHz 3 dB bandwidth. This two element design can be reconfigured for wider bandwidth, high-pass response, or bypassed altogether.

Power Supplies

FPGA 1.2 V core supply has been reconfigured on LLRF4.6. The new switching regulator is based on the LTC3604 from Linear Technologies. Here is a comparison of the new device with the MAX1820X used on LLRF4.2:

	MAX1820X	LTC3604	Units
Output current	0.6	2.5	A
Switching frequency	1	2 (up to 4)	MHz
External sync	Direct	PLL	
Sync frequency	10–16 ($\div 13$)	0.8–4	MHz

The FPGA user I/O pin labeled "SYNC" in the UCF provides the optional synchronization function. Existing designs that used this feature based on the MAX1820X will need to be adapted to the different characteristics of the new regulator chip.

One major problem with the MAX1820X was that changes in external sync drive created large output voltage transients, locking up the FPGA (high power dissipation, no JTAG/USB response). For those reasons, few designs made use of the synchronization capability. With a synchronization PLL, LTC3604 can seamlessly go from free running to synchronized mode and back to free running. Direct synchronization drive (without divide-by-13 as in the MAX1820X) provides for more a flexible FPGA divide ratio.

Another power supply related change in LLRF4.6 is the deletion of 8 power output jumpers. These made sense early on, but not at serial numbers above 100. Jumpers have been replaced by zero ohm 0603 parts, so the regulators can still be disconnected from the loads, if necessary.

LVDS inter-board communication

Since Spartan-6 supports internal differential termination for LVDS, on-board termination resistors have been deleted. Direction and termination options can be specified in HDL code now.

Unfortunately, Xilinx does not support bi-directional LVDS I/O with runtime termination control. So the bit files have to explicitly define inputs and outputs, enabling termination for the inputs. Since the signals are flipped on the cable, it is feasible to define 4 output channels and 4 input channels, with identical bitfile on both FPGAs.

Connector Summary

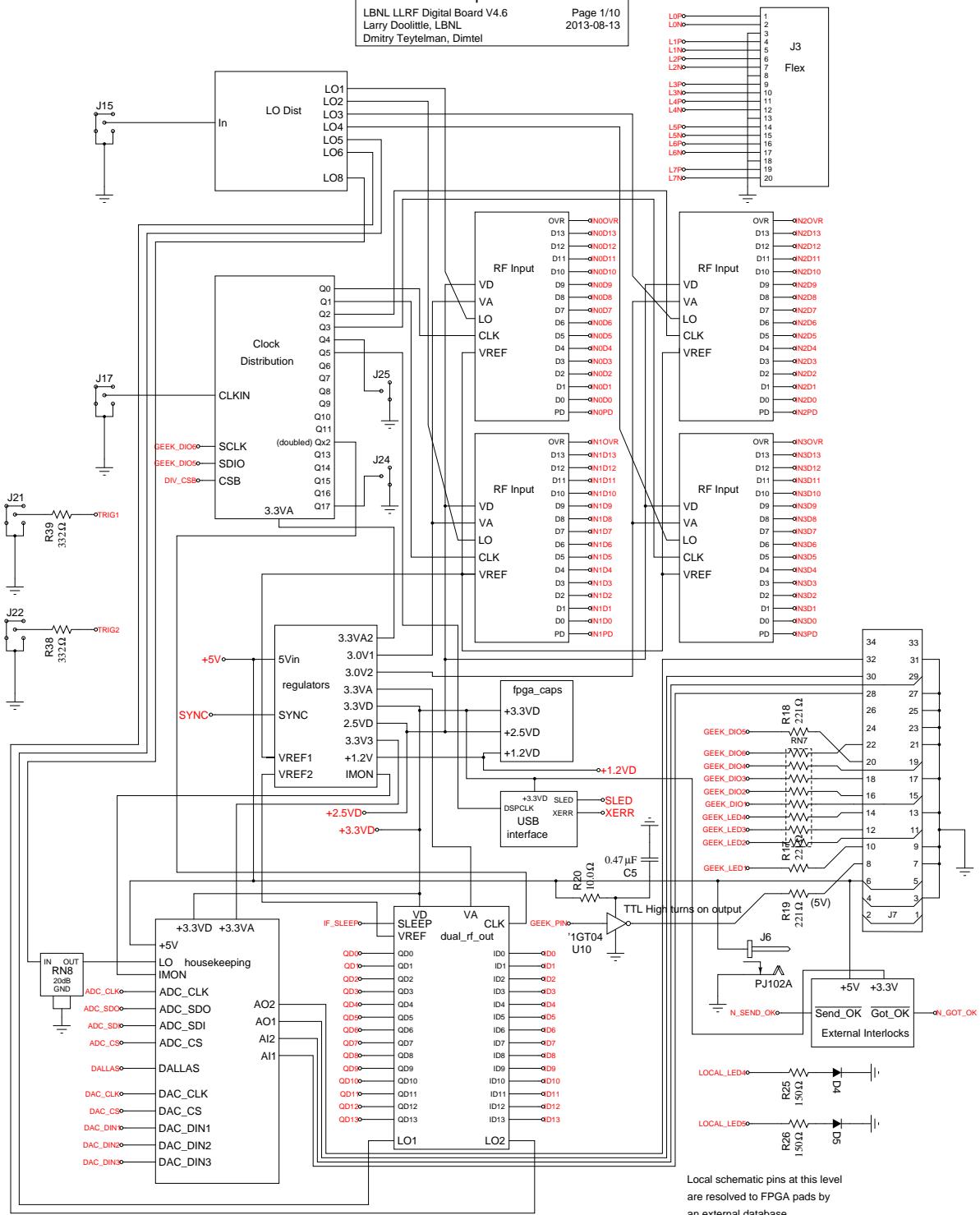
Counterclockwise around the perimeter of the board

J101	SMA	RF/IF input
J201	SMA	RF/IF input
J301	SMA	RF/IF input
J401	SMA	RF/IF input
J15	SMA	LO input (+26 dBm nominal)
J17	SMA	Clock input (+1 dBm nominal)
J7	34-pin header	Geek port (see schematic)
J18	SMA	RF/IF output
J19	SMA	RF/IF output
J20	SMA	Analog output (0 to 2.5V, 2.2 k Ω)
J9	24-pin header	12 channels Analog output (0 to 2.5V)
J8	6-pin Weidmuller	SNS-compatible interlock I/O
J21	LEMO	Trigger
J22	LEMO	Trigger
J6	2.1 mm	+5V, 1.2A pseudo-regulated power input
J1	Type B	USB
J3	20-pin 0.5mm flex	LVDS inter-board communication

Interior test points

J23	U.Fl	LO monitor (remove R809 to maintain match)
J24	U.Fl	ICS83940D output 17
J25	U.Fl	ICS83940D output 4
J26	U.Fl	AD9512 output 3
J27	2mm	IF output channel 2
J28	2mm	IF output channel 1

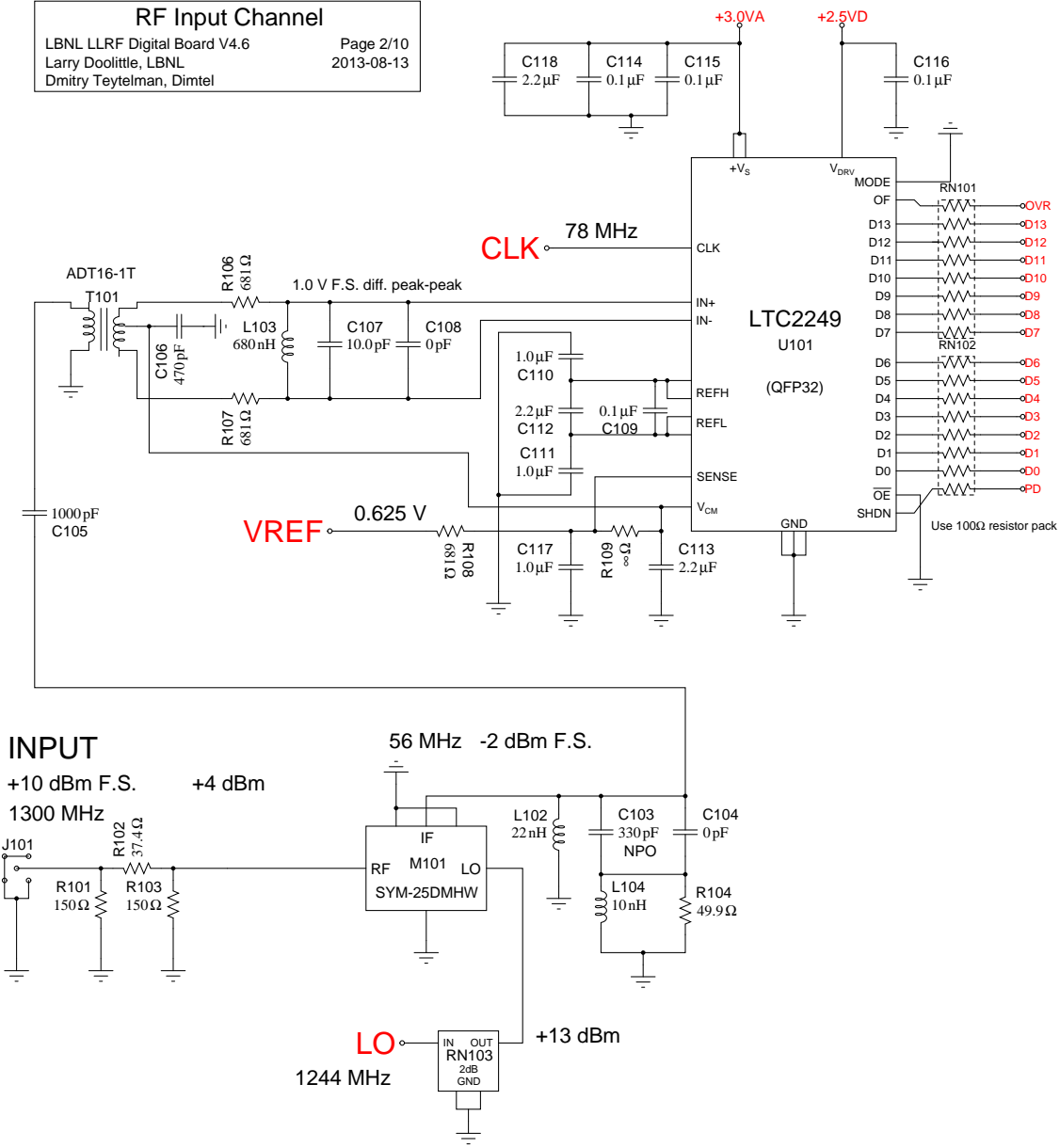
2mm test points are intended for use with a high-impedance single-ended FET scope probe.



Local schematic pins at this level are resolved to FPGA pads by an external database.

RF Input Channel
 LBNL LLRF Digital Board V4.6
 Larry Doolittle, LBNL
 Dmitry Teytelman, Dimtel

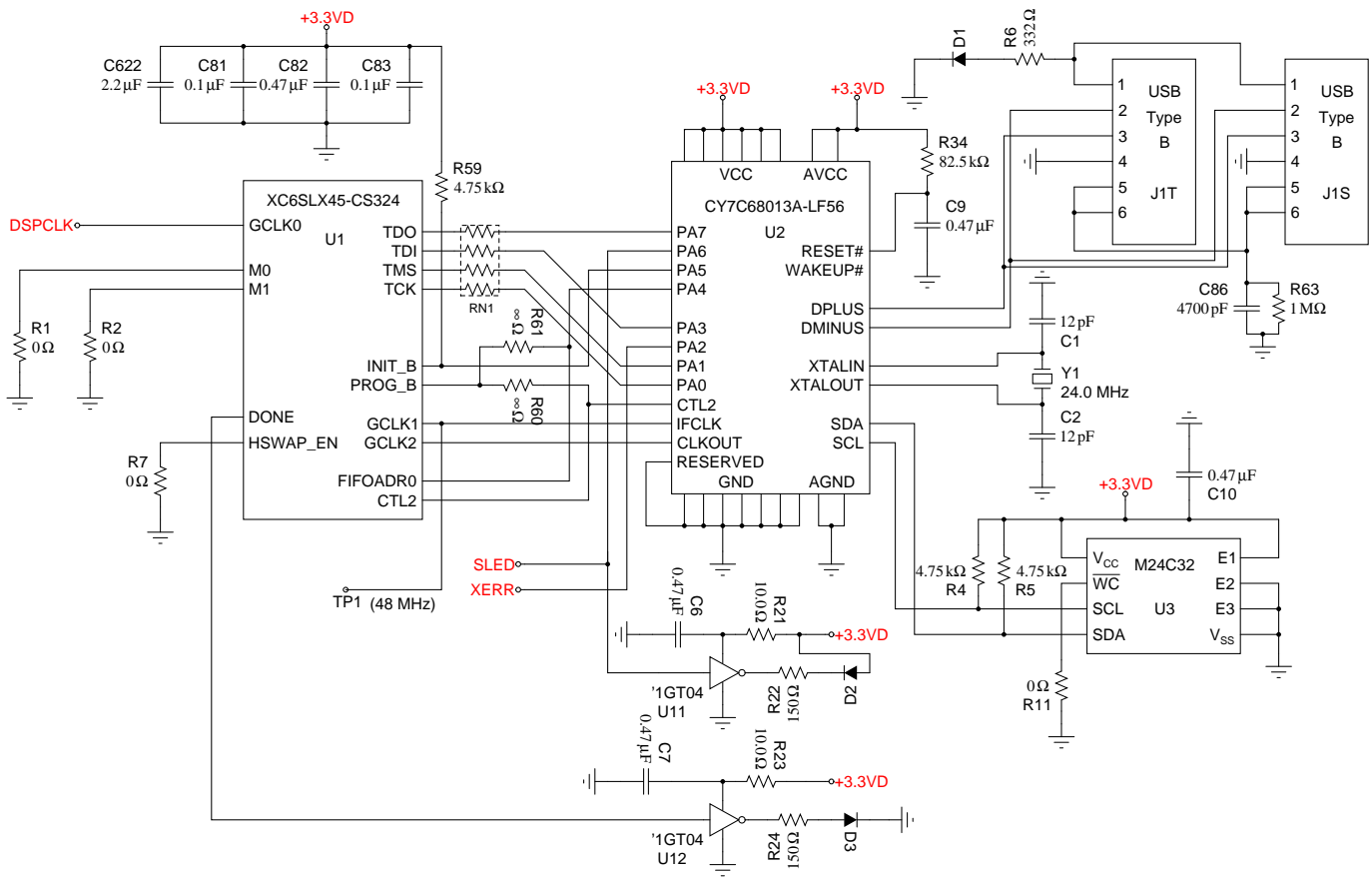
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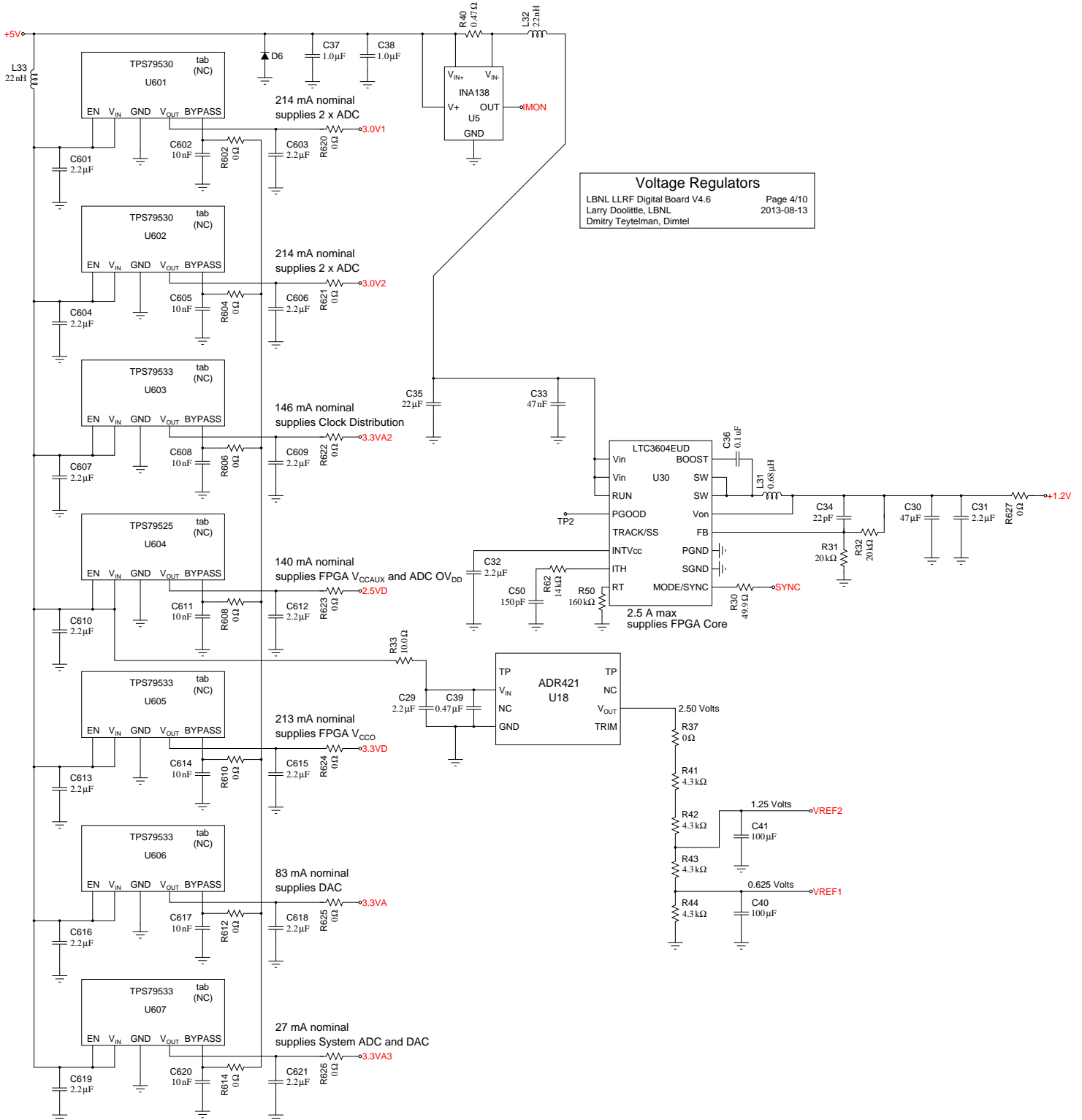


USB Interface

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Voltage Regulators
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LTC3604EUD
 U30
 2.5 A max
 supplies FPGA Core

ADR421
 U18

214 mA nominal
 supplies 2 x ADC

214 mA nominal
 supplies 2 x ADC

146 mA nominal
 supplies Clock Distribution

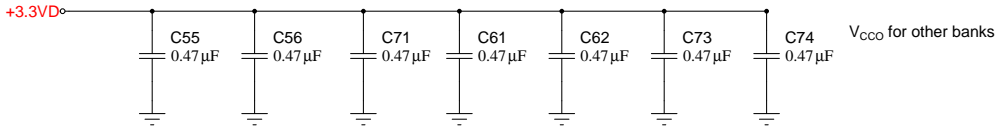
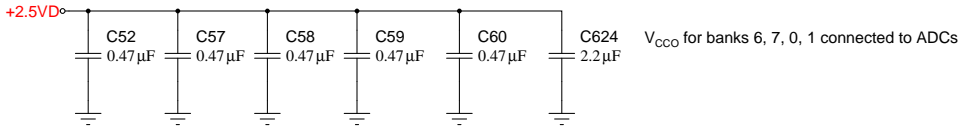
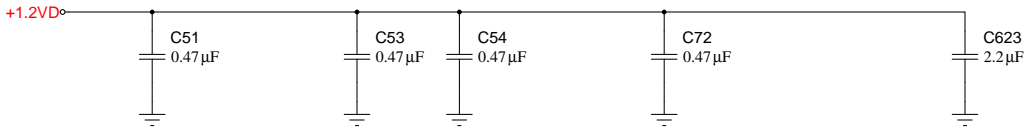
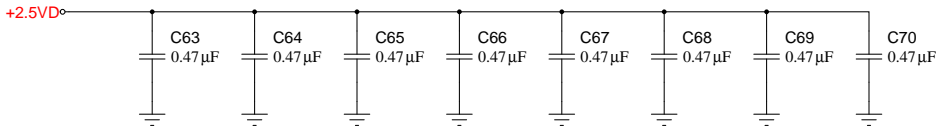
140 mA nominal
 supplies FPGA V_{CCAUX} and ADC OV_{DD}

213 mA nominal
 supplies FPGA V_{CCO}

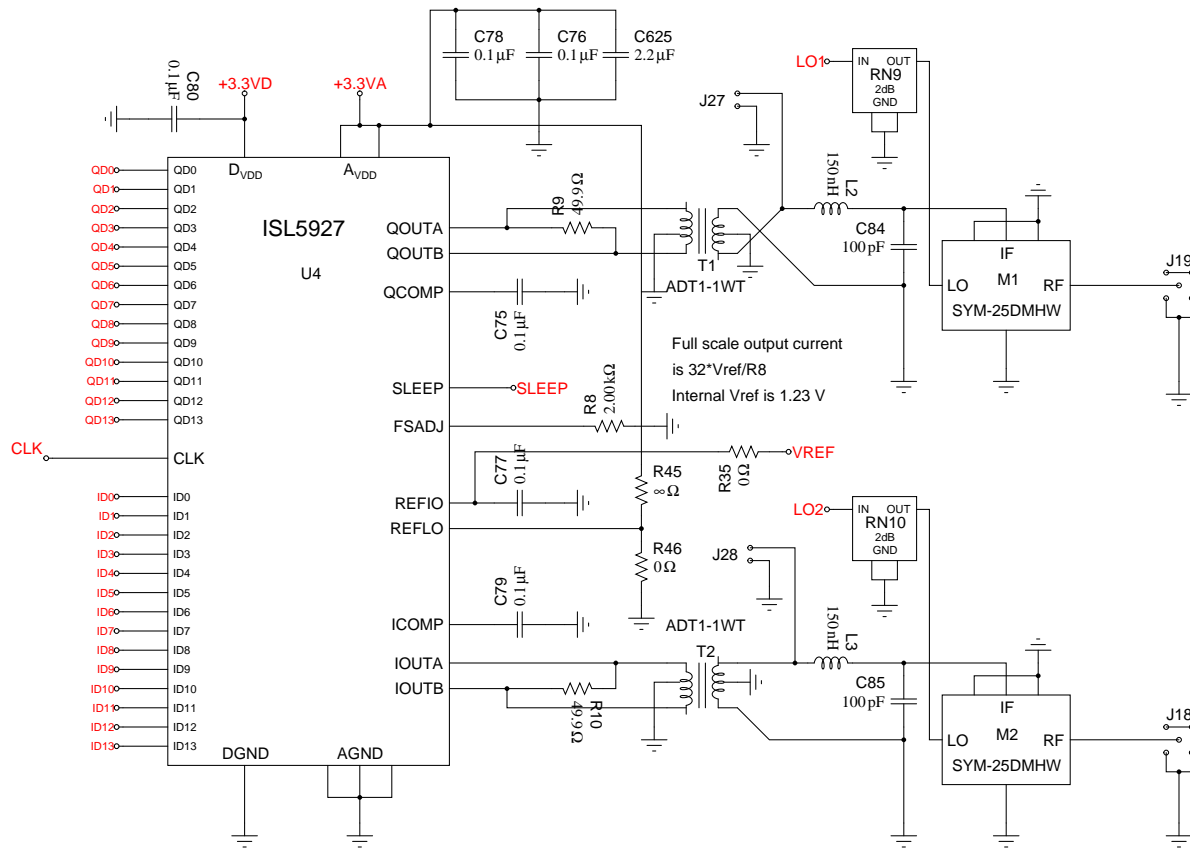
83 mA nominal
 supplies DAC

27 mA nominal
 supplies System ADC and DAC

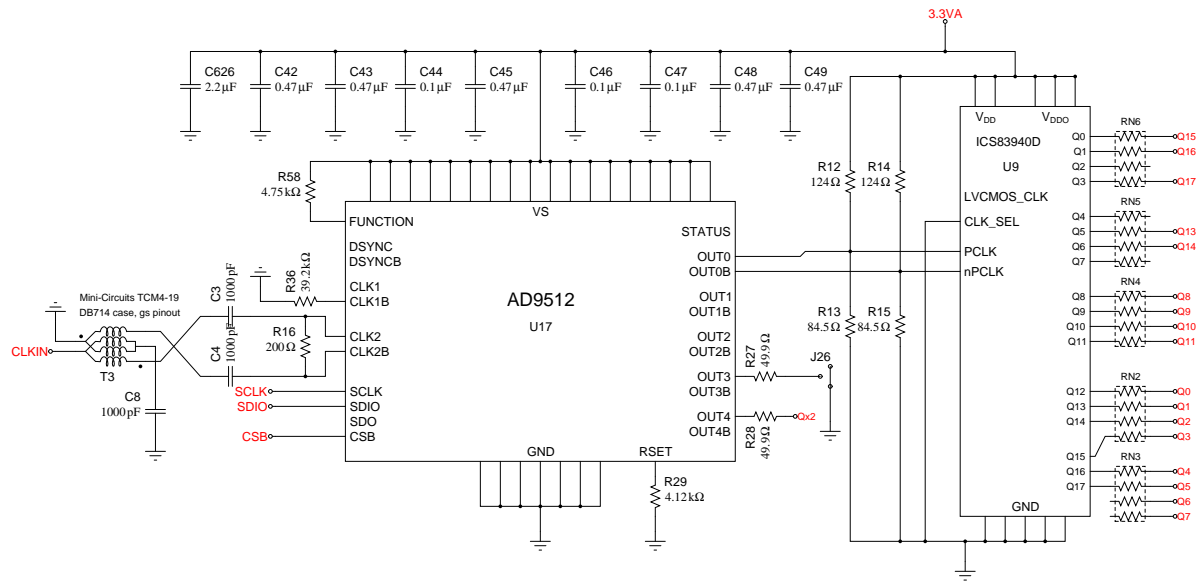
FPGA Power Capacitors
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 Dmitry Teytelman, Dimtel

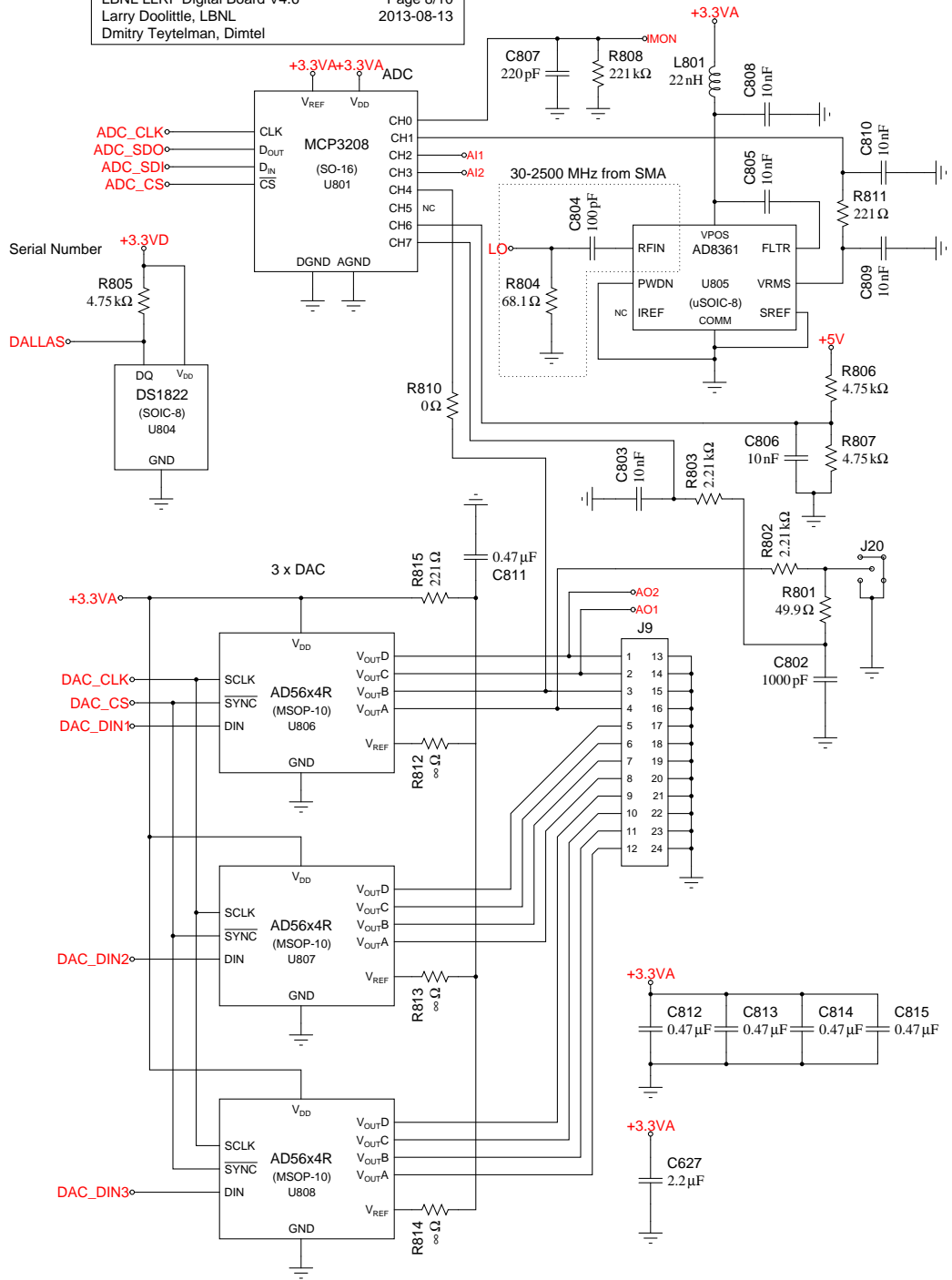


RF Output Channels
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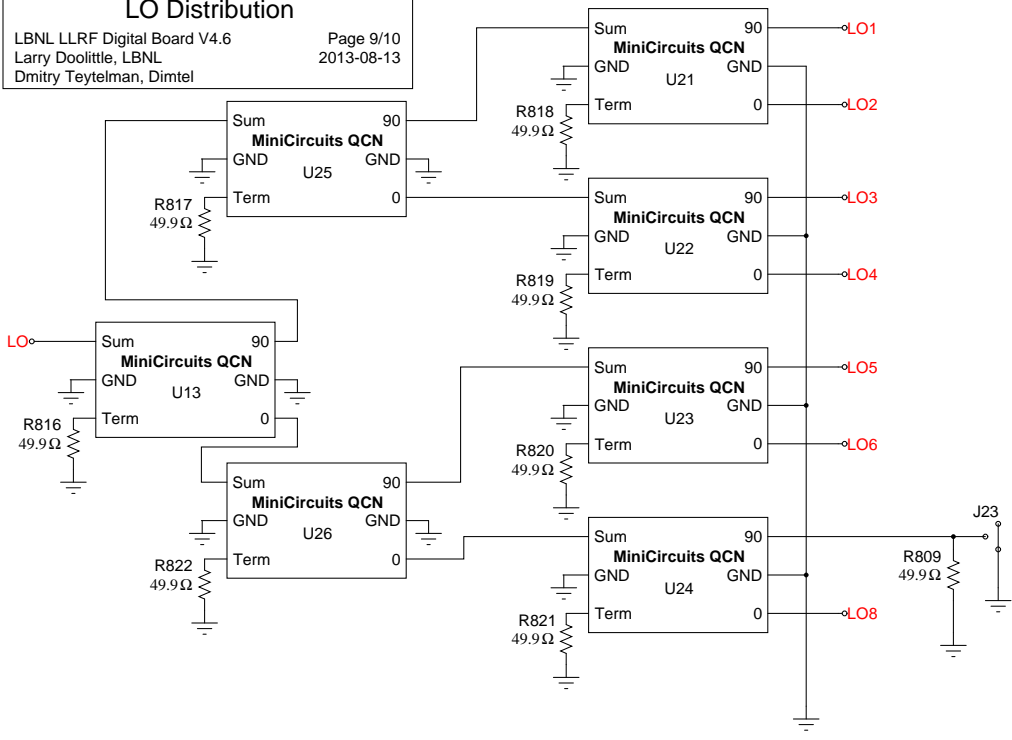


Clock Distribution
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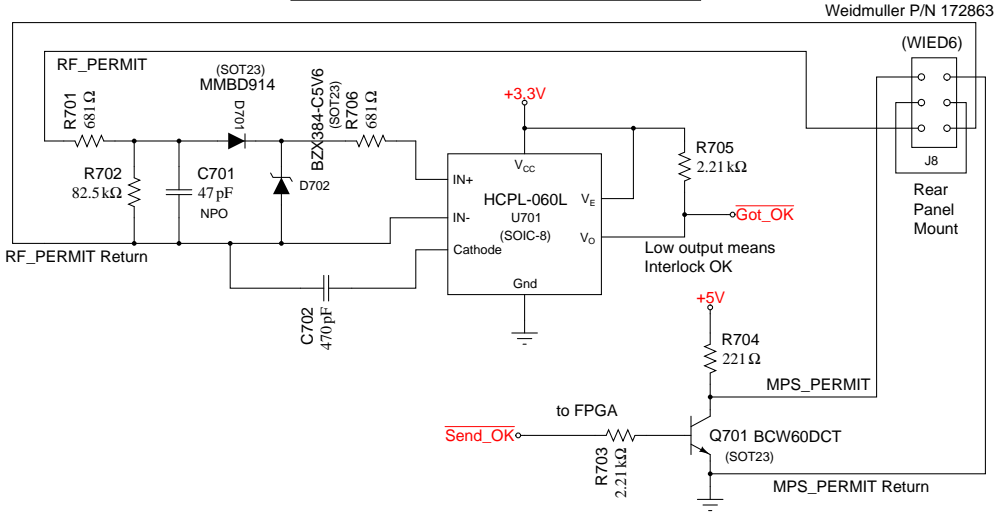


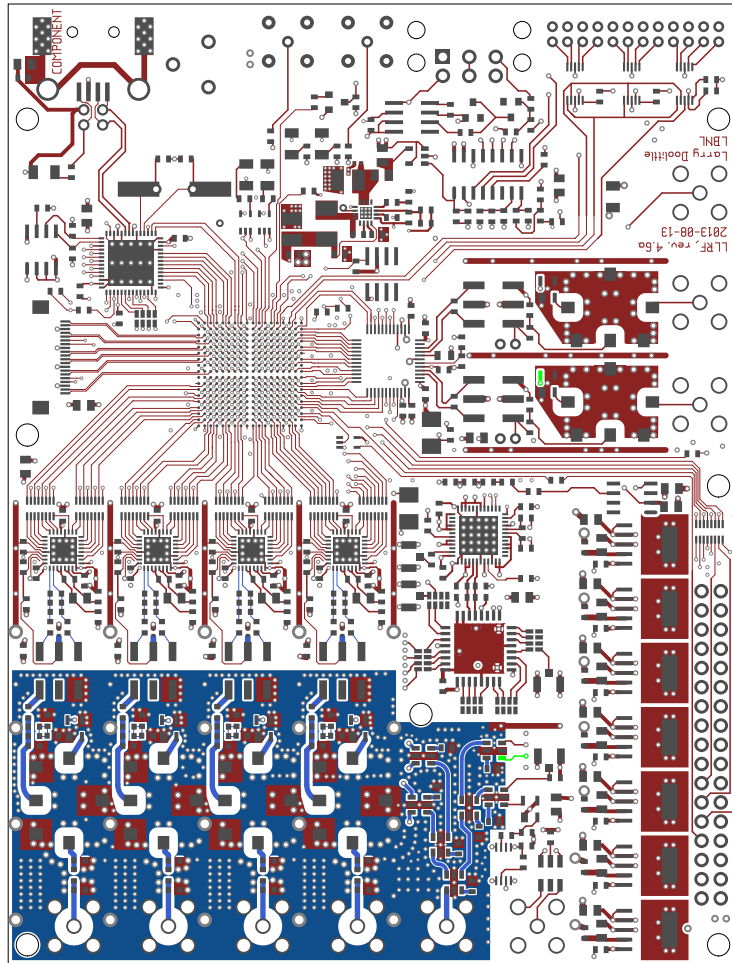


LO Distribution
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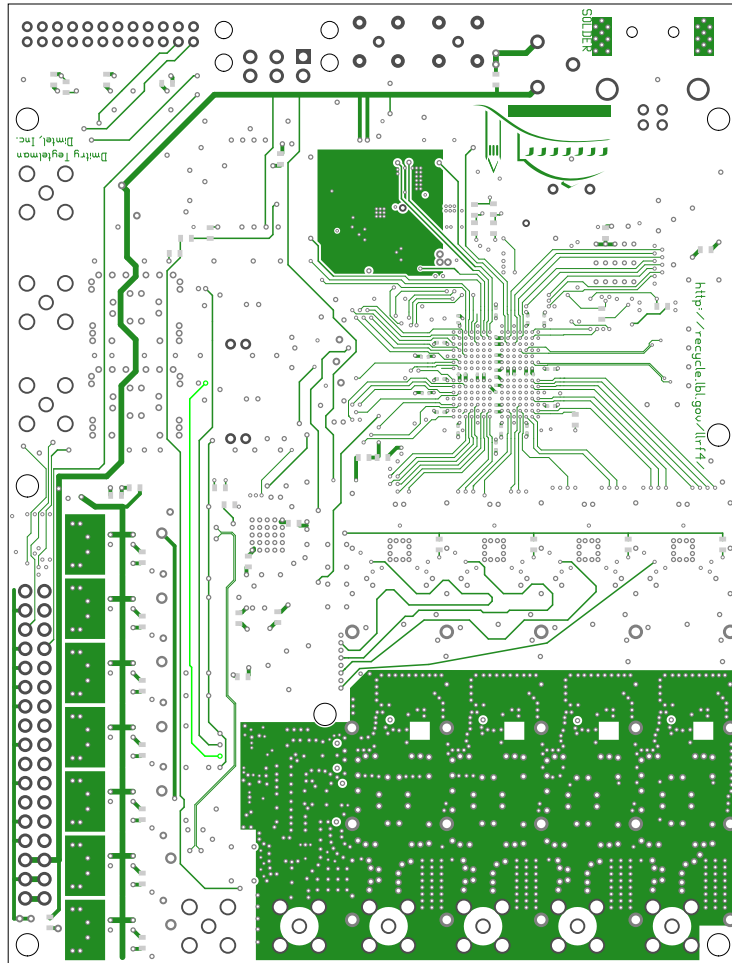


Interlock Input/Output
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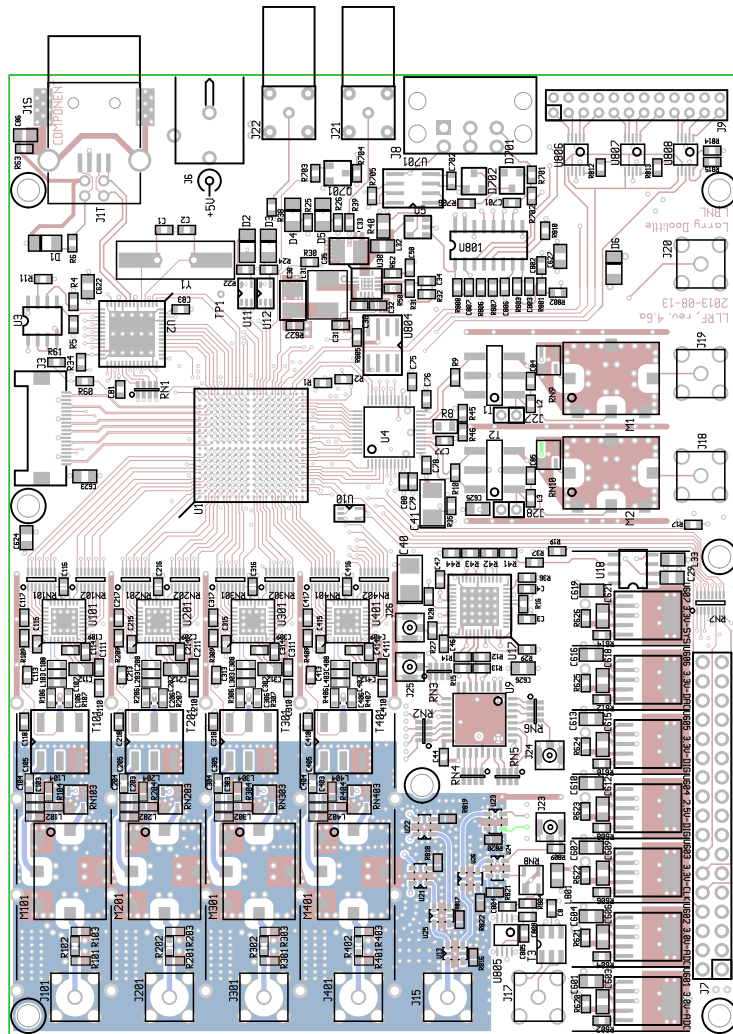




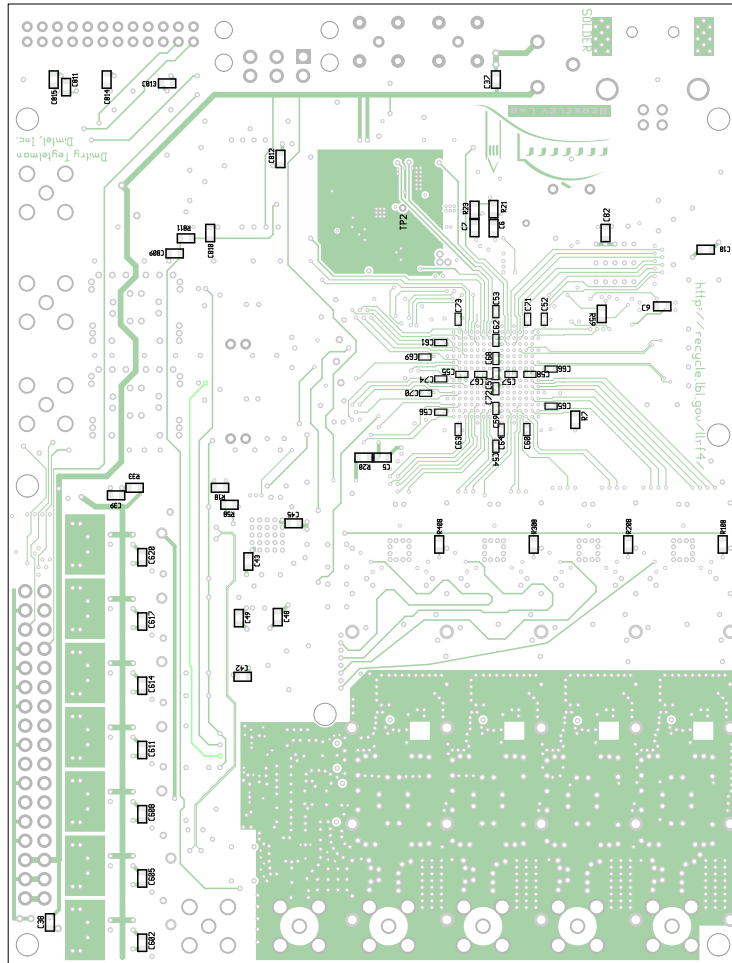
LLRF4, top, scale = 1:1.000
llrf4.pcb



LLRF4, bottom (mirrored), scale = 1:1.000
llrf4.pcb



LLRF4, topassembly, scale = 1:1.000
llrf4.pcb



LLRF4, bottomassembly (mirrored), scale = 1:1.000
llrf4.pcb

There are 16 different drill sizes used in this layout, 1831 holes total

Symbol Diam. (Inch) Count Plated?

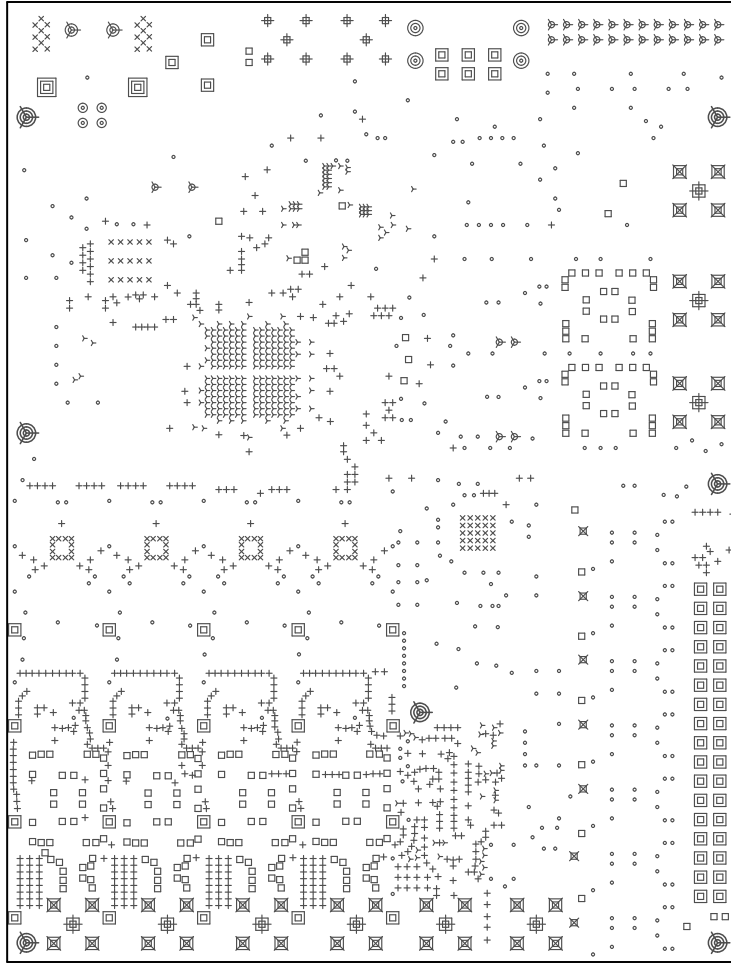
γ	0.009	307	YES
+	0.012	657	YES
x	0.014	106	YES
o	0.015	368	YES
□	0.020	219	YES
▽	0.030	30	YES
#	0.032	10	YES
⊗	0.035	7	YES
⊙	0.036	4	YES
⊖	0.045	63	YES
⊕	0.055	2	NO
⊗	0.061	9	YES
⊙	0.067	36	YES
⊖	0.090	4	NO
⊕	0.091	2	YES
⊗	0.116	7	NO

Title: LLRF4 - Fabrication Drawing

Author: Dmitry Teytelman

Date: Tue 13 Aug 2013 05:45:48 PM GMT UTC

Maximum Dimensions: 5000.000000 mils wide, 3600.000000 mils high



Board outline is the centerline of this 8.000000 mil rectangle - 0.0 to 5000.000000, 3600.000000 mils